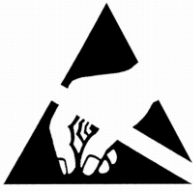
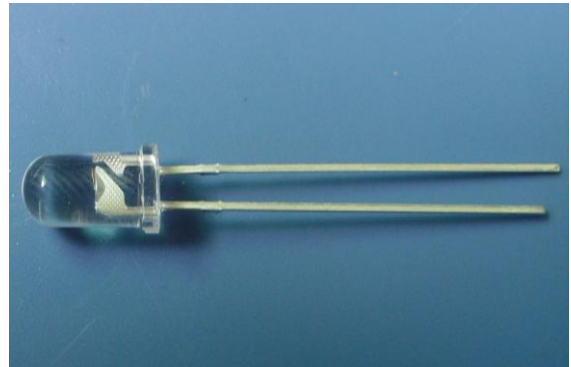


HL-503S11GC



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

HL-503S11GC



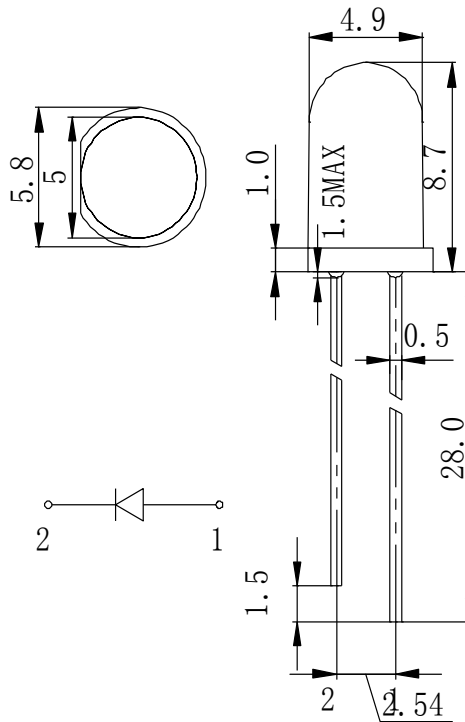
Features

- φ 5 LAMP LED
- LOW POWER CONSUMPTION.
- CABINED VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- PACKAGE: 1000PCS / BAG.

Package Dimensions

Description

This devices are made with TS AllnGP



Tolerance Grade	Dimension Tolerance (UNIT:mm)			
	0.5~3	3~6	6~30	30~120
	±0.1	±0.2	±0.3	±0.5
Chip		Lens Color		
Material	Emitting Color	Water Clear		
AllnGP	Greenish Yellow			

■ Absolute Maximum Rating

Item	Symbol	Value	Unit
Forward Current	I _F	20	mA
Peak Forward Current*	I _{FP}	100	mA
Reverse Voltage	V _R	5	V
Power Dissipation	P _D	80	mW
Electrostatic discharge	E _{SD}	2000	V
Operation Temperature	T _{opr}	-30~+80	°C
Storage Temperature	T _{stg}	-30~+80	°C
Lead Soldering Temperature*	T _{sol}	Max. 260°C for 5sec Max.	

*I_{FP} Conditions: Pulse Width ≤ 10msec

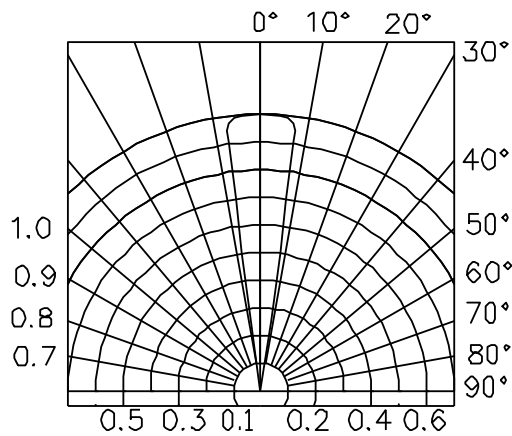
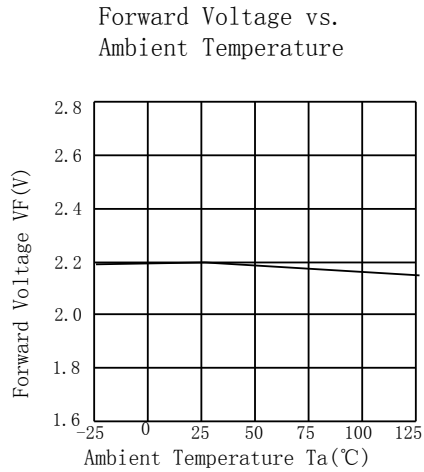
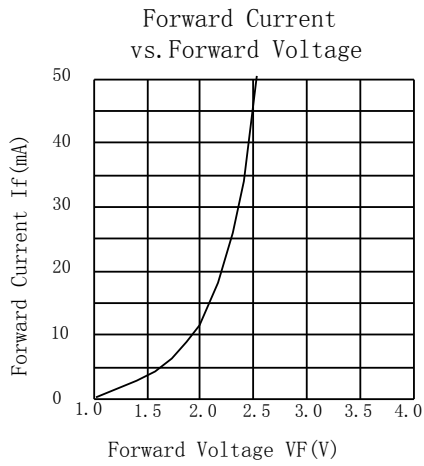
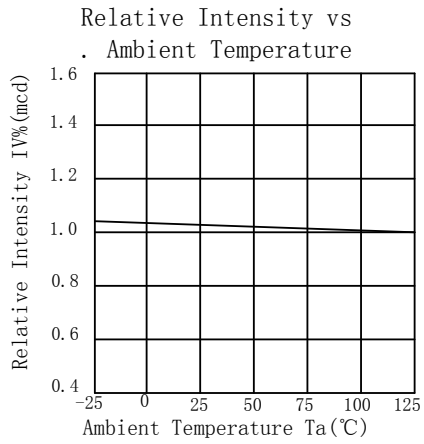
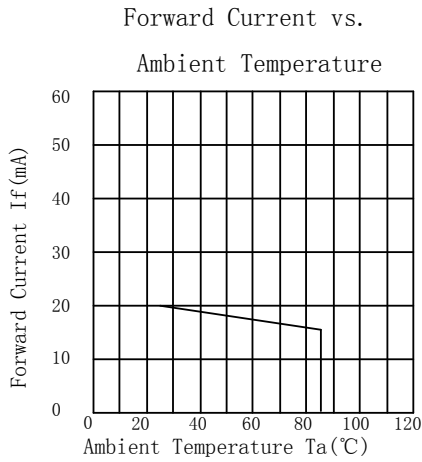
*T_{sol} Conditions: 3mm from the base of the epoxy bulb

■ Typical Optical/ Electrical Characteristics Ta=25°C

Item	Symbol	Condition	Rank	Min.	Typ.	Max.	Unit
Luminous Intensity	I _v	I _F =20mA	T	1320		1715	mcd
			U	1715		2230	mcd
			V	2230		2900	mcd
			W	2900		3770	mcd
			X	3770		4900	mcd
Forward Voltage	V _F			1.8	2.2	2.6	V
Viewing Angle	2θ 1/2			--	15	--	deg
Prpc Wavelength	λ _D			565	--	575	nm
Recommend Forward Current	I _{F(rec)}	--		--	--	20	mA
Reverse Current	I _R	V _r =5V		--	--	20	uA

Notes:

Tolerance : V_F ± 0.1V, λ_d ± 2 nm, I_v(φ V) ± 15%, 2θ 1/2 ± 15%



Soldering:

1. Manual Of Soldering

The temperature of the iron tip should not be higher than 300°C and Soldering within 3 seconds per solder-land is to be observed.

2. DIP soldering (Wave Soldering):

Preheating: 120°C~150°C, within 120~180 sec.

Operation heating: 245°C ± 5°C within 5 sec. 260°C (Max)

Gradual Cooling (Avoid quenching).

